

IN THE CLAIMS

1. (Currently Amended) A method of fabricating an ~~electron source~~ image display apparatus comprising the steps of:

fixing a first sealing member to a first substrate disposed with an electroconductive member, the first sealing member surrounding the electroconductive member ~~excepting~~ except for a portion of the electroconductive member;

abutting a chamber having a gas inlet port and a gas exhaust port on the first sealing member to cover the electroconductive member ~~excepting~~ except for the portion of the electroconductive member and form a hermetically sealed atmosphere between the first substrate and the chamber;

supplying power to the portion of the electroconductive member to give part of the electroconductive member covered with the chamber an electron-emitting function;

[[and]]

removing the chamber from the first substrate; and

bonding the first substrate with a second substrate on which an image forming member is disposed, wherein the bonding is performed on the first sealing member fixed to the first substrate.

2. (Original) A method according to claim 1, wherein the electroconductive member includes wiring lines and an electroconductive film with an electron-emitting area connected to the wiring lines.

3. (Original) A method according to claim 2, wherein a plurality of electroconductive films are formed.
4. (Original) A method according to claim 3, wherein the plurality of electroconductive films are interconnected in a matrix shape by the wiring lines.
5. (Currently Amended) A method according to claim 1, wherein ~~[[said]]~~ the power-supplying step of supplying power is performed in a low pressure atmosphere.
6. (Currently Amended) A method according to claim 1, wherein ~~[[said]]~~ the power-supplying step of supplying power is performed in a reducing gas atmosphere.
7. (Currently Amended) A method according to claim 6, wherein a reducing gas of the reducing gas atmosphere is hydrogen.
8. (Currently Amended) A method according to claim 1 wherein ~~[[said]]~~ the power-supplying step of supplying power is performed in an atmosphere which contains organic material.
9. (Currently Amended) A method according to claim 1, wherein ~~[[said]]~~ the power-supplying step of supplying power includes a first power supplying step to be

performed in a reducing gas atmosphere and a second power supplying step to be performed in an atmosphere which contains organic material.

10. (Canceled)

11. (Original) A method according to claim 1, wherein the first sealing member is frit glass.

12. (Original) A method according to claim 1, wherein the first sealing member includes adhesive and a support frame bonded to the substrate with adhesive.

13. (Original) A method according to claim 12, wherein the adhesive is frit glass.

14. (Original) A method according to claim 12, wherein the adhesive is indium or its alloy.

15. (Original) A method according to claim 1, wherein a second sealing member is interposed between the first sealing member and the chamber.

16. (Original) A method according to claim 15, wherein the second sealing member is made of organic elastic material.

17. (Canceled)

18. (Currently Amended) A method according to claim [[17]] 1, wherein the bonding step uses a third sealing member.

19. (Currently Amended) A method ~~according to claim 18, further comprising a cleaning step~~ of fabricating an image forming apparatus comprising the step of:

bonding an electron source and a substrate disposed with image forming members, wherein the electron source is fabricated by a method comprising the steps of:

fixing a first sealing member to a substrate disposed with an electroconductive member, the first sealing member surrounding the electroconductive member except for a portion of the electroconductive member,

abutting a chamber on the first sealing member to cover the electroconductive member except for the portion of the electroconductive member and form a hermetically sealed atmosphere between the substrate and the chamber,

supplying power to the portion of the electroconductive member to
give part of the electroconductive member covered with the chamber an electron-emitting
function, and

removing the chamber from the first substrate,

wherein the bonding step uses a third sealing member, and

further comprising a cleaning step of cleaning the first sealing member
before the bonding step, by dismounting the chamber from the substrate of the electron
source.

20. (Currently Amended) A method according to claim 19, wherein
[[said]] the cleaning step uses MEK (methyl-ethyl-ketone).

21. (Currently Amended) A method according to claim 19, wherein
[[said]] the cleaning step uses HFE (hydro-fluoro-ether).

22. (Currently Amended) A method according to claim 19, wherein
[[said]] the cleaning step uses MEK (methyl-ethyl-ketone) and HFE (hydro-fluoro-ether).

23. (Currently Amended) A method according to claim 18, wherein the
third sealing member is an ~~second~~ adhesive.

24. (Currently Amended) A method according to claim 23, wherein the ~~second~~ adhesive is frit glass.

25. (Currently Amended) A method according to claim 23, wherein the ~~second~~ adhesive is indium or its alloy.

26. (Canceled)

27. (Currently Amended) A system for fabricating an electron source to be used by the method according to any one of claims ~~[[1 to 16]]~~ 1-9 and 11-16, comprising:

means for supporting the substrate disposed with the electroconductive member with an electrostatic chuck; and

means for making a predetermined atmosphere in the chamber abutted on the first sealing member.

28. (Original) A system according to claim 27, further comprising means for supplying power to the electroconductive member.

29. - 35. (Canceled)